

Abstract

Provided is a method of polishing a substrate in which a surface with high flatness and few defects can be realized with high efficiency. The method of polishing a substrate provided according to the present invention includes a plurality of stock polishing sub-steps that are performed by supplying a first polishing solution, a second polishing solution, and a third polishing solution in this order in a stock polishing step of a substrate. The relationships between a content COM_{P1} of a water-soluble polymer P_1 contained in the first polishing solution, a content COM_{P2} of a water-soluble polymer P_2 contained in the second polishing solution, and a content COM_{P3} of a water-soluble polymer P_3 contained in the third polishing solution satisfy $COM_{P1} < COM_{P2} < COM_{P3}$, and any one of the following conditions is satisfied: (1) the average primary particle diameter D_{A3} of abrasive A_3 contained in the third polishing solution is smaller than the average primary particle diameter D_{A1} of abrasive A_1 contained in the first polishing solution and the average primary particle diameter D_{A2} of abrasive A_2 contained in the second polishing solution; and (2) the third polishing solution does not contain abrasive A_3 .